Product data sheet

1. **Product profile**

1.1 General description

Hyperfast, epitaxial rectifier diode in a SOD113 (2-lead TO-220F) plastic package.

1.2 Features

- Extremely fast switching
- Low reverse recovery current
- Reduces switching loss in associated **MOSFET**
- Low thermal resistance
- Isolated package

1.3 Applications

- Half-bridge or full-bridge switched-mode Continuous Current Mode (CCM) Power power supplies
- Half-bridge lighting ballasts
- Factor Correction (PFC)

1.4 Quick reference data

- $V_{RRM} \le 600 \text{ V}$
- $V_F = 1.40 \text{ V (typ)}$

- $I_{F(AV)} \le 5 A$
- $t_{rr} = 19 \text{ ns (typ)}$

Pinning information

Pinning Table 1.

Pin	Description	Simplified outline	Symbol
1	cathode (k)		. 14
2	anode (a)	mb	k — a 001aaa020
mb	mounting base; isolated		
		SOD113 (2-lead TO-22	0F)

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3. Ordering information

Table 2. Ordering information

Type number	Package		
	Name	Description	Version
BYC5X-600	TO-220F	plastic single-ended package; isolated heatsink mounted; 1 mounting hole; 2-lead TO-220 'full pack'	SOD113

4. Limiting values

Table 3. Limiting values

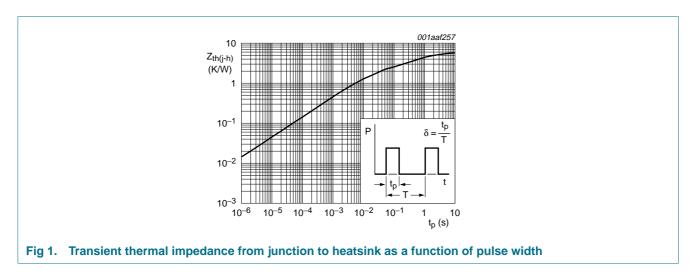
In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Min	Max	Unit
V_{RRM}	repetitive peak reverse voltage		-	600	V
V_{RWM}	crest working reverse voltage		-	600	V
V_R	reverse voltage	square waveform; δ = 1.0; $T_h \le 100~^{\circ}C$	-	500	V
I _{F(AV)}	average forward current	square waveform; δ = 0.5; $T_h \leq 87~^{\circ}C$	-	5	Α
I_{FRM}	repetitive peak forward current	square waveform; δ = 0.5; $T_h \leq 87~^{\circ}C$	-	10	Α
	non-repetitive peak forward	t = 10 ms; sinusoidal waveform	-	40	Α
	current	t = 8.3 ms; sinusoidal waveform	-	44	Α
T _{stg}	storage temperature		-40	+150	°C
T _i	junction temperature		-	150	°C

5. Thermal characteristics

Table 4. Thermal characteristics

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
$R_{th(j-h)}$	thermal resistance from junction to heatsink	with heatsink compound; see Figure 1	-	-	5.5	K/W
		without heatsink compound	-	-	7.2	K/W
R _{th(j-a)}	thermal resistance from junction to ambient	in free air	-	60	-	K/W



6. Isolation characteristics

Table 5. Isolation limiting values and characteristics

 $T_h = 25 \,^{\circ}C$ unless otherwise specified.

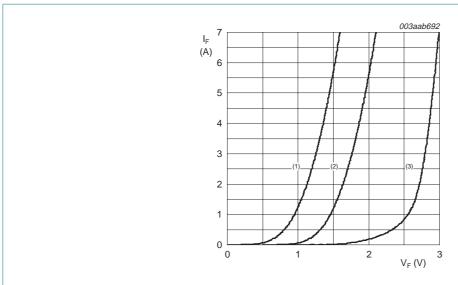
Symbol	Parameter	Conditions	Min	Тур	Max	Unit
$V_{\text{isol}(\text{RMS})}$	RMS isolation voltage	from all terminals to external heatsink; $f = 50 \text{ Hz}$ to 60 Hz; sinusoidal waveform; relative humidity $\leq 65 \%$; clean and dust free	-	-	2500	V
C _{isol}	isolation capacitance	from cathode to external heatsink; f = 1 MHz	-	10	-	pF

7. Characteristics

Table 6. Characteristics

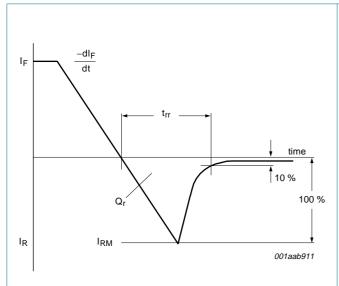
 $T_j = 25 \,^{\circ}C$ unless otherwise specified.

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
Static characteristics						
V _F forward	forward voltage	$I_F = 5 \text{ A}$; $T_j = 150 ^{\circ}\text{C}$; see Figure 2	-	1.40	1.75	V
		$I_F = 10 \text{ A}; T_j = 150 ^{\circ}\text{C}; \text{ see } \frac{\text{Figure 2}}{}$	-	1.75	2.20	V
		I _F = 5 A; see <u>Figure 2</u>	-	2.00	2.90	V
I _R	reverse current	V _R = 600 V	-	9	100	μΑ
		$V_R = 500 \text{ V}; T_j = 100 ^{\circ}\text{C}$	-	0.9	3.0	mΑ
Dynamic o	characteristics					
t _{rr}	reverse recovery time	I_F = 1 A to V_R = 30 V; dI_F/dt = 50 A/ μ s; see Figure 3	-	30	50	ns
		$I_F = 5 \text{ A to } V_R = 400 \text{ V};$ $dI_F/dt = 500 \text{ A/}\mu\text{s}; \text{ see } \frac{\text{Figure 3}}{}$	-	19	-	ns
		I_F = 5 A to V_R = 400 V; dI_F/dt = 500 A/ μ s; T_j = 100 °C; see <u>Figure 3</u>	-	25	30	ns
I _{RM}	peak reverse recovery current	I_F = 5 A to V_R = 400 V; dI_F/dt = 50 A/ μ s; T_j = 125 °C; see <u>Figure 3</u>	-	0.7	3	Α
		I_F = 5 A to V_R = 400 V; dI_F/dt = 500 A/ μ s; T_j = 100 °C; see <u>Figure 3</u>	-	8	11	Α
V_{FR}	forward recovery voltage	$I_F = 10 \text{ A}$; $dI_F/dt = 100 \text{ A/}\mu\text{s}$; see Figure 4	-	9	11	V



- (1) $T_j = 150 \,^{\circ}\text{C}$; typical values
- (2) $T_j = 150 \,^{\circ}\text{C}$; maximum values
- (3) $T_j = 25$ °C; maximum values

Fig 2. Forward current as a function of forward voltage





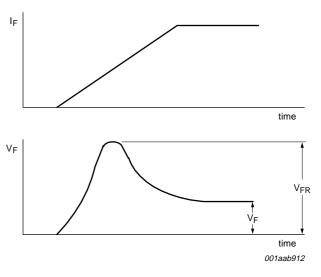


Fig 4. Forward recovery definitions

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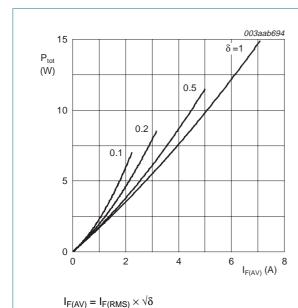
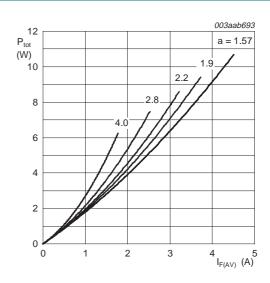


Fig 5. Forward power dissipation as a function of average forward current; square waveform; maximum values



 $a = form \ factor = I_{F(RMS)} / I_{F(AV)}$

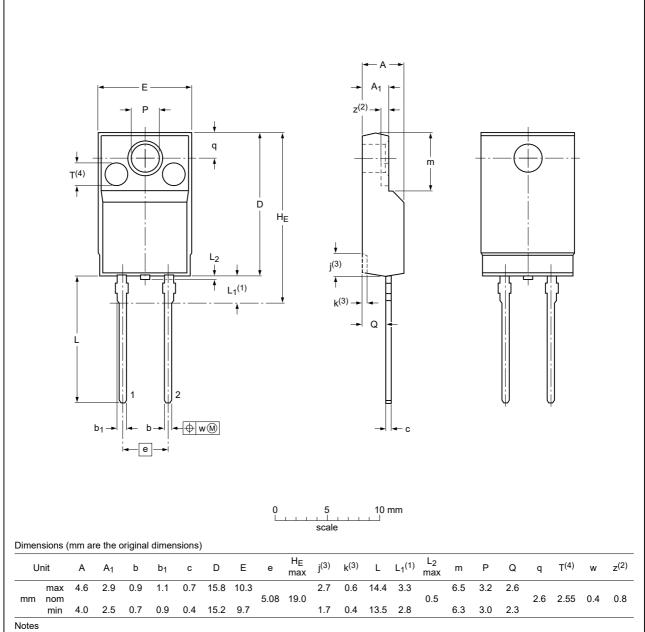
Fig 6. Forward power dissipation as a function of average forward current; sinusoidal waveform; maximum values

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Package outline

Plastic single- ended package; isolated heatsink mounted; 1 mounting hole; 2- lead TO- 220 'full pack'

SOD113



- 1. Terminals are uncontrolled within zone L1.
- 2. z is depth of T.
- 3. Dot lines area designs may vary.
- 4. Eject pin mark is for reference only.

sod113_po

Outline	References			European	Issue date	
version	IEC	JEDEC	JEITA		projection	issue date
SOD113		2-lead TO-220F				-07-06-08 15-08-28



Hyperfast power diode

9. Legal information

Data sheet status

Document status [1][2]	Product status [3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

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BYC5X-600

Hyperfast power diode

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